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FDMS86500L

N-Channel PowerTrench[®] MOSFET 60 V, 158 A, 2.5 m Ω

Features

- Max $r_{DS(on)} = 2.5 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 25 \text{ A}$
- Max $r_{DS(on)} = 3.7 \text{ m}\Omega$ at $V_{GS} = 4.5 \text{ V}$, $I_D = 20 \text{ A}$
- \blacksquare Advanced Package and Silicon combination for low $r_{\text{DS(on)}}$ and high efficiency
- Next generation enhanced body diode technology, engineered for soft recovery
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant

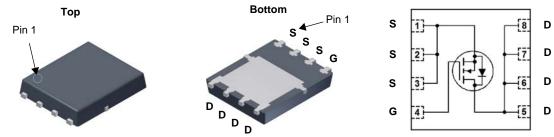


General Description

This N-Channel MOSFET has been designed specifically to improve the overall efficiency and to minimize switch node ringing of DC/DC converters using either synchronous or synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low $r_{DS(on)}$, fast switching speed and body diode reverse recovery performance.

Applications

- Primary Switch in Isolated DC-DC
- Synchronous Rectifier
- Load Switch



Power 56

MOSFET Maximum Ratings $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter			Ratings	Units
V_{DS}	Drain to Source Voltage			60	V
V_{GS}	Gate to Source Voltage			±20	V
I _D	Drain Current -Continuous	T _C = 25 °C	(Note 5)	158	
	-Continuous	T _C = 100 °C	(Note 5)	100	A
	-Continuous	T _A = 25 °C	(Note 1a)	25	A
	-Pulsed		(Note 4)	799	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	240	mJ
P_{D}	Power Dissipation	Dissipation $T_C = 25 ^{\circ}C$		104	W
	Power Dissipation	T _A = 25 °C	(Note 1a)	2.5	VV
T _J , T _{STG}	Operating and Storage Junction Temperature Range			-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.2	°C/W
$R_{\theta,JA}$	Thermal Resistance, Junction-to-Ambient (No	ote 1a)	50	C/VV

Package Marking and Ordering Information

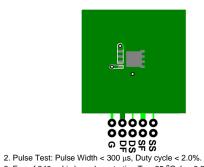
Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS86500L	FDMS86500L	Power 56	13 "	12 mm	3000 units

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chara	cteristics			•	•	
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	60			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, referenced to 25 °C		30		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 48 V, V _{GS} = 0 V			1	μА
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
On Chara	cteristics			-	-	
$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$ 1		1.8	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \mu A$, referenced to 25 °C		-7		mV/°C
		V _{GS} = 10 V, I _D = 25 A		2.1	2.5	
r _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 4.5 V, I _D = 20 A		2.9	3.7	mΩ
		V _{GS} = 10 V, I _D = 25 A, T _J = 125 °C		3.1	3.7	
9 _{FS}	Forward Transconductance	V _{DS} = 5 V, I _D = 20 A		95		S
Dynamic	Characteristics				+	
C _{iss}	Input Capacitance			9420	12530	pF
C _{oss}	Output Capacitance	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V},$		1470	1955	pF
C _{rss}	Reverse Transfer Capacitance	f = 1 MHz		50	80	pF
R _q	Gate Resistance		0.1	1.1	3.0	Ω
	Characteristics		"	"		1
t _{d(on)}	Turn-On Delay Time			27	43	ns
t _r	Rise Time	$V_{DD} = 30 \text{ V}, I_D = 25 \text{ A},$		16	28	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$		63	100	ns
t _f	Fall Time			7.8	16	ns
Q _q	Total Gate Charge	V _{GS} = 0 V to 10 V		117	165	nC
Qg	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 30 \text{ V},$		54	108	nC
Q _{gs}	Gate to Source Charge	I _D = 25 A		26.6		nC
Q _{gd}	Gate to Drain "Miller" Charge			11.5		nC
Drain-Sοι	rce Diode Characteristics					
I _s	Continuous Drain to Source Diode Forward Current	T _C = 25 °C			80	А
I _{s, pluse}	Pluse Drain to Source Diode Forward Current	T _C = 25 °C			799	А
V _{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 2.1 \text{ A}$ (Note 2) $V_{GS} = 0 \text{ V}, I_S = 25 \text{ A}$ (Note 2)	'	0.68 0.79	1.2 1.3	V
t _{rr}	Reverse Recovery Time			54	87	ns
Q _{rr}	Reverse Recovery Charge	$I_F = 25 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s}$		42	67	nC
t _{rr}	Reverse Recovery Time	1 05 A 11/11 000 A		46	73	ns
Q _{rr}	Reverse Recovery Charge			84	134	nC

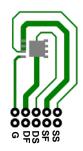
Vrr Qrr Reverse Recovery Charge

Notes:

1. R_{0JA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0CA} is determined by the user's board design.



a) 50 °C/W when mounted on a 1 in² pad of 2 oz copper



b) 125 °C/W when mounted on a minimum pad of 2 oz copper.

- 3. E_{AS} of 240 mJ is based on starting T_J = 25 °C, L = 0.3 mH, I_{AS} = 40 A, V_{DD} = 54 V, V_{GS} = 10 V. 100% test at L = 0.1 mH, I_{AS} = 66 A. 4. Pulsed ld please refer to Fig 11 SOA graph for more details.
- 5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

Typical Characteristics $T_J = 25$ °C unless otherwise noted.

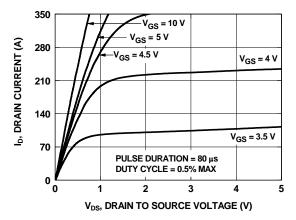


Figure 1. On-Region Characteristics

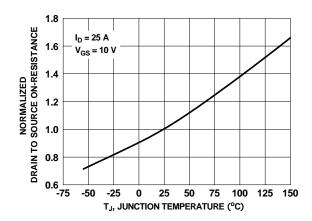


Figure 3. Normalized On-Resistance vs. Junction Temperature

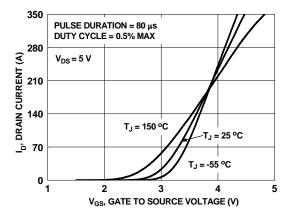


Figure 5. Transfer Characteristics

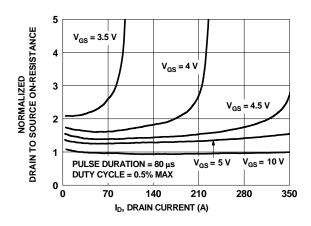


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

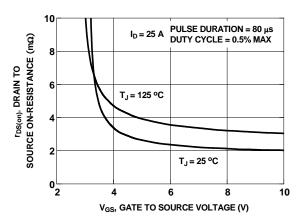


Figure 4. On-Resistance vs. Gate to Source Voltage

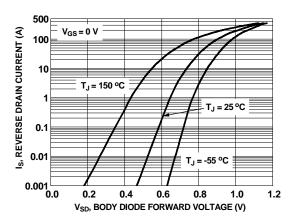


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted.

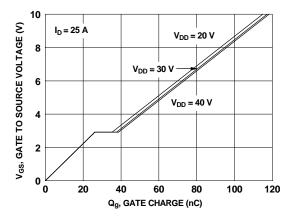


Figure 7. Gate Charge Characteristics

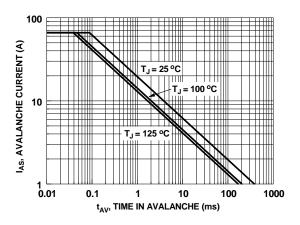


Figure 9. Unclamped Inductive Switching Capability

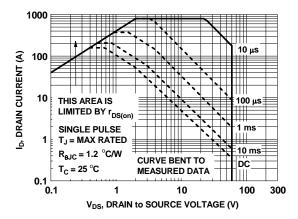


Figure 11. Forward Bias Safe Operating Area

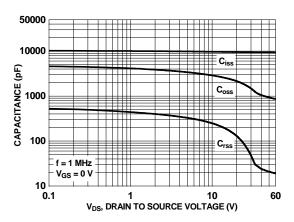


Figure 8. Capacitance vs. Drain to Source Voltage

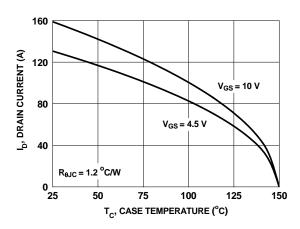


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

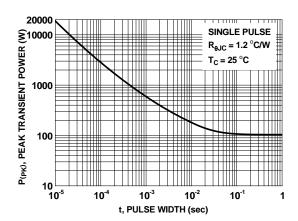


Figure 12. Single Pulse Maximum Power Dissipation



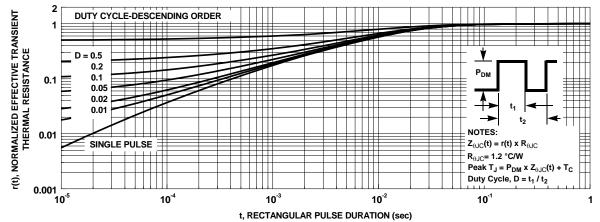
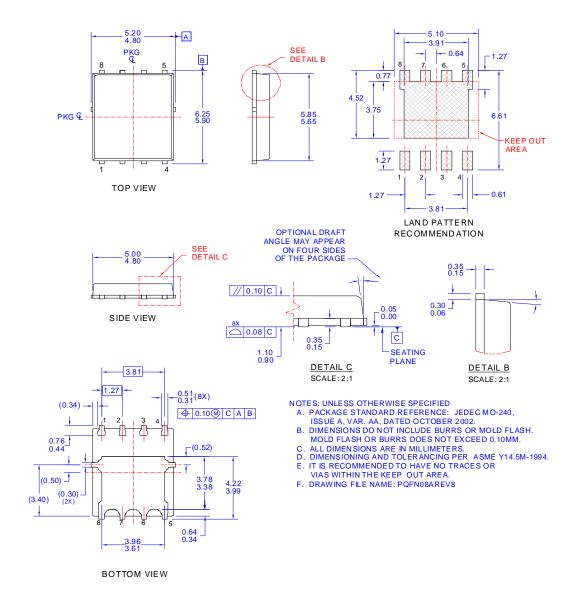
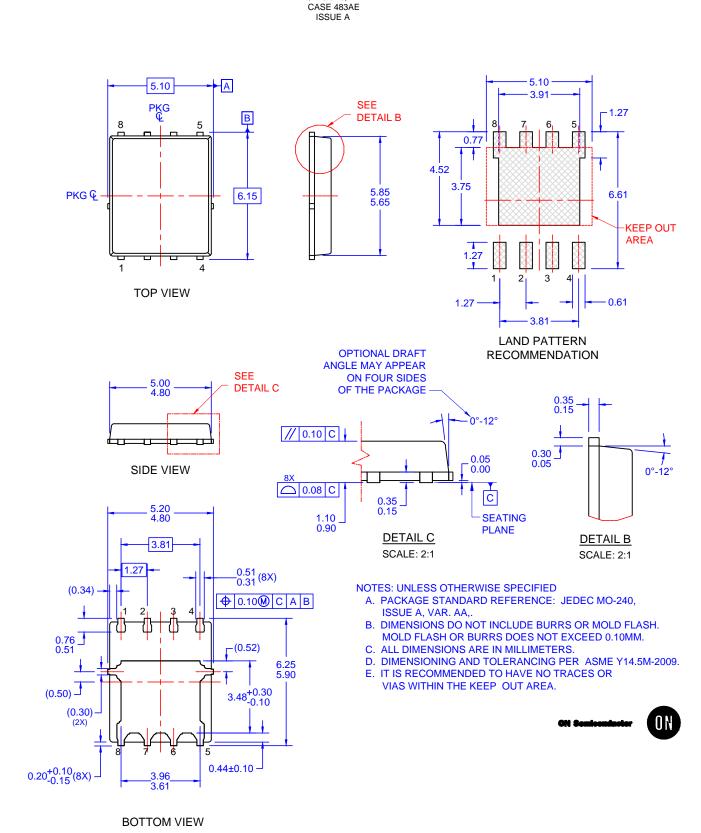


Figure 13. Junction-to-Case Transient Thermal Response Curve

Dimensional Outline and Pad Layout



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